

REMARKS

Claims 14-16 and 21-23 were examined on the merits. The remaining claims were withdrawn as the result of a restriction requirement. Applicant requests that, in the event claim 16 is allowed, that dependent claims 17-20 be allowed as well. Similarly, in the event claim 21 is allowed, dependent claims 24-26 should also be allowed.

Claims 33-34 have been added.

In the Office action, claims 14-16 and 21-23 were rejected as anticipated by U.S. Patent No. 6,445,271 (Johnson). As discussed below, applicant respectfully requests reconsideration.

The Office action apparently fails to appreciate that “wire bonding” and “wire bonds” are phrases that have well-defined meanings in the art, and that those meanings are consistent with the way that phrase is used in the pending application. The interpretation of “wire bonding” and “wire bonds” as implied by the Office action is contrary to the ordinary meaning as a person of ordinary skill in the art would understand those phrases. Indeed, as discussed below, the interpretation is also contrary to the use of the phrase “wire-bond” as used in the Johnson patent.

In the context of the pending application, a person of ordinary skill would understand that “wire bonding” is a technique that involves forming an interconnection with a thin wire. See B. Streetman, *Solid State Electronic Devices*, pp. 368-371 (Prentice-Hall 1980, 2nd ed.) (copies attached). Particular examples of wire bonding include die bonding, thermocompression bonding and ultrasonic bonding. *Id.* Those same examples are expressly mentioned in the pending specification at page 6, lines 10-12.

The pending claims are not limited to the particular details of “wire bonding” disclosed in the Streetman text. However, it is clear that a person of ordinary skill in the art would understand that the Johnson patent does not disclose “wire bonding” and “wire bonds” in connection with formation of the inductor coil(s).

Instead, the Johnson patent (US 6,445,271) forms the inductor coil(s) by solder bonding together a substrate 11 and a wafer 13, each of which has a conductive pattern (16, 17) on its

surface corresponding to portions of the inductor coil(s). The patterned layer 16 of metal on the upper wafer 13 (FIG. 1B) does not include wire bonds, and wire bonding is not used to form the inductor coil(s) in the Johnson patent.

The Johnson patent does, in fact, use the phrase “wire-bond,” but not in connection with formation of the inductor itself. As stated in the Johnson patent, “For connections to external circuitry . . . , inductor 12 . . . can be connected to wire-bond pads 22” (*see* col. 5, lines 48). In other words, although the inductor 12 itself is not formed using wire bonds, it can be connected to pads 22 using wire bonds, which allow the inductor to be coupled to external circuitry. That use of “wire-bond” is consistent with the way that phrase ordinarily is used in the field and, furthermore, is consistent with the way it is used in the pending claims. In any event, that use of the phrase “wire-bond” in the Johnson patent makes it clear that wire bonds and wire bonding are not used to form the inductor coil(s) in the Johnson patent.

At least for the foregoing reasons, the pending claims are not anticipated by, or suggested by, the Johnson patent.

Applicant also points out that the office action apparently misinterpreted the following feature recited in claim 21: “wire bonds interconnecting portions of the conductive lines to define a plurality of windings”

Based on the remarks at the top of page 3, the Office action appears to have understood that language as if the phrase “wire bonds interconnecting portions” referred to certain portions called “wire bonds interconnecting” portions. That is clearly incorrect in view of the claim language itself and the rest of the specification. Instead, the cited claim language refers to wire bonds that interconnect portions of the conductive lines.

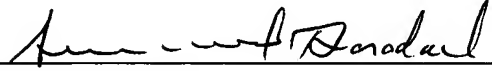
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Enclosed is a check for excess claim fees. Please apply any other charges or credits to deposit account 06-1050.

Respectfully submitted,

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